

Session Title:	[WB1] Material Issues in Semiconductor Fabrication
Session Date:	November 16 (Wed.), 2022
Session Time:	10:45-12:15
Session Room:	Room B (Grand Ballroom 1, 2F)
Session Chair:	Prof. Hyunseop Lee (Dong-A Univ., Korea)

[WB1-1] 10:45-11:05

Bulk Silicon Etching Technology for Wafer Thinning Applied in Next Generation Memory Device

Jung Sik Oh, Myung Ho Lee, Myung Geun Song, and Woo Jae Lee (ENF Tech. Co., Ltd., Korea)

[WB1-2] 11:05-11:25

Study on Wet Cleaning Solutions Behavior on the Wafer Surface during the Single Cleaning Process

Chengxi Yao, Kihong Park, Jinhyoung Lee, Pengzhan Liu, Sanghuck Jeon (Sungkyunkwan Univ., Korea), and Youngki Ahn (Daelim Univ. College, Korea)

[WB1-3] 11:25-11:45

Extremely High Selective $\text{Si}_{1-x}\text{Ge}_x$ -film Wet Etchant Generating Highly Dissolved Oxygen via Peracetic Acid Oxidant for Lateral Gate-All-Around FET with a Logic Node of Less Than 3-nm

Seung-Jae Lee, Ji-Eun Lee, Chang-Jin Lee, and Jea-Gun Park (Hanyang Univ. Korea)

[WB1-4] [Invited] 11:45-12:15

Overall Requirements for Wet Chemical and CMP Materials in Foundry Business

Inyu Jung, Ahn-Ho Lee, Choong-Ho Han, and Yun-Ho Kim (Samsung Electronics Co., Ltd., Korea)